

### Description

The SI7106DN-T1-E3 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### **General Features**

V<sub>DS</sub> = 20V I<sub>D</sub> =60A

 $R_{DS(ON)} < 5m\Omega$  @ V<sub>GS</sub>=4.5V

### Application

Battery protection

Load switch Uninterruptible power supply

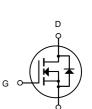
### Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SI7106DN-T1-E3	DFN3X3-8L	HXY MOSFET	5000

#### Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	20	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	60	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	33	А
Ідм	Pulsed Drain Current <sup>2</sup>	220	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	46	mJ
las	Avalanche Current	25	А
P₀@Tc=25°C	Total Power Dissipation <sup>4</sup>	15	W
Тѕтд	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R <sub>0</sub> JA	Thermal Resistance Junction-ambient <sup>1</sup>	62	°C/W
R <sub>θ</sub> JC	Thermal Resistance Junction-Case <sup>1</sup>	4.5	°C/W





DFN3X3-8L

N-Channel MOSFET

N-Channel Enhancement Mode MOSFET

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{DS}$ =0V, $V_{GS}$ =±12V	-	-	±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	0.4	0.7	1.1	V
Р	Static Drain-Source on-Resistance V <sub>GS</sub> =4.5V, I <sub>D</sub> =30A	V <sub>GS</sub> =4.5V, I <sub>D</sub> =30A	-	4.0	5	mΩ
$R_{\text{DS(on)}}$	note3	V <sub>GS</sub> =2.5V, I <sub>D</sub> =20A	-	6.0	9	
Ciss	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f = 1.0MHz	-	2500	-	pF
Coss	Output Capacitance		-	407	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	386	-	pF
Qg	Total Gate Charge	V <sub>DS</sub> =10V, I <sub>D</sub> =30A, V <sub>GS</sub> =4.5V	-	32	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	3	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	11	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	$V_{DS}$ =10V, I <sub>D</sub> =30A, R <sub>GEN</sub> =3Ω,	-	17	-	ns
tr	Turn-on Rise Time		-	49	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	74	-	ns
t <sub>f</sub>	Turn-off Fall Time	V <sub>GS</sub> =4.5V	-	26	-	ns
l.	Maximum Continuous Drain to Source	imum Continuous Drain to Source Diode Forward			75	А
Is	Current		-	-	75	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	300	А
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> =30A	-	-	1.2	V

# **Electrical Characteristics** (TJ=25°C unless otherwise specified)

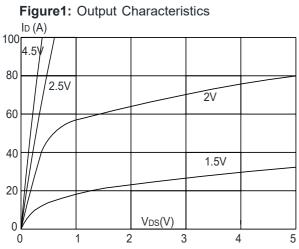
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

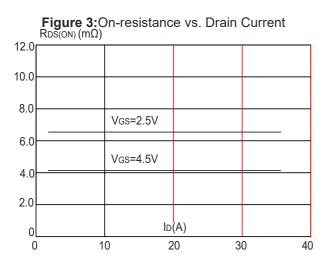
2. EAS condition: T\_J=25  $^\circ\!\!\mathrm{C}$  , V\_DD=10V, V\_G=4.5V, L=0.5mH, R\_G=25  $^\Omega$  , I\_{AS}=15A

3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%

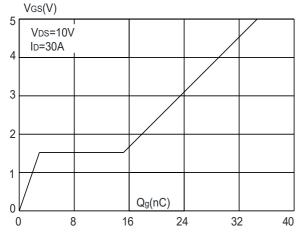


# **Typical Performance Characteristics**



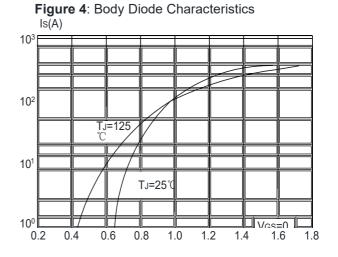


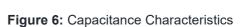


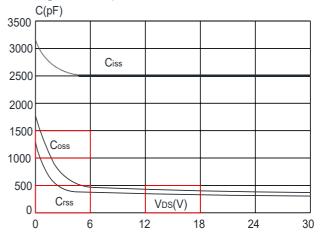


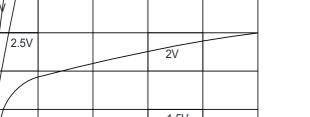
ID (A) 100 80 60 **125℃** 40 **25℃** 20 ′¢s(V) 0 0.5 1.0 1.5 2.0 2.5 3.0 0

Figure 2: Typical Transfer Characteristics











Junction Temperature VBR(DSS) 1.3 1.2 1.1 1.0 0.9 Tj(℃) 0 -100 -50 0 50 100 200 150

Figure 7: Normalized Breakdown Voltage vs.

Figure 9: Maximum Safe Operating Area

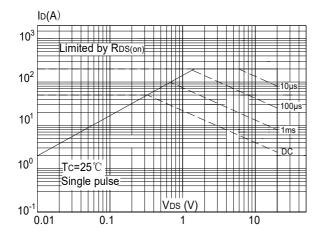
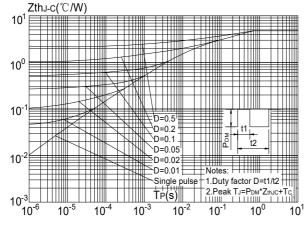
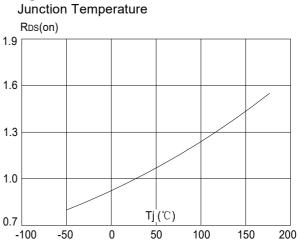


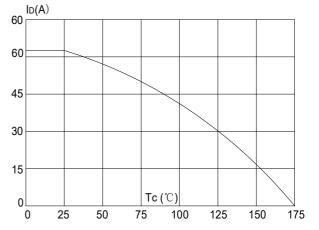
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case





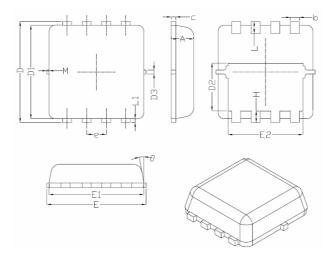
# Figure 8: Normalized on Resistance vs.

### Figure 10: Maximum Continuous Drain Current vs. Case Temperature





## **DFN3X3-8L Package Information**



Symphol	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
e	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
М	*	*	0.15	
θ		10 <sup>°</sup>	12 <sup>°</sup>	



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